IPC ASSOCIATION CONNEC	Material Compo © Copyright 2005. II international and Pan	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfc Information			
upplier Info										,		-			
Company name* Company unique ID					τ	Unique ID Authority					Response Date*				
nsemi											2025-	2025-05-13			
Contact Name Title				Fitle - Contact			Phone - Contact*				Emai	Email - Contact*			
Product-Env-Ste	ewards	Product Enviro Compliance				NA				Prod	Product-Env-Stewards@onsemi.com				
Authorized Representative* Title				Citle - Representative			Phone - Representative*			Emai	Email - Representative*				
Product-Env-Stewards Product Enviro Compliance						NA				Prod	Product-Env-Stewards@onsemi.com				
Reque	ester Item Number	Mfr Item	em Number Mfr Item Nan		,		Effective Date	e Vers	ion	Manufacturing Site		Weight*	UOM	Unit Type	
		ASX340A D0-TPBF	AT2C00XPE	VGA 1/4 SOC			2025-05-13			TWU		108.93	mg	Each	
Ianufacturin	ng Proccess Informat	tion													
Termin	Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020			J-STD-020 MS	L Rating	Peak Pro	cess Bod	ly Temperati	ıre Max Time at I	eak Tempe	rature Num	ber of Reflow Cy	cles		
SnAgCu		CU Alloy 3			260	C 30		sec	onds 3						
omments															
TTENTION: M	ISL 3 Rated item requires	s Bake and D	ry Pack (after	electrical test)											
or more inform	ation regarding material	composition 1	please refer to	page 3										·	

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	23.9	mg		Misc.	proprietary data		0.0908	mg
			Supplier	Silicon (Si)	7440-21-3		23.5726	mg
			Supplier	Aluminum (Al)	7429-90-5		0.2366	mg
Die Attach	2.2	mg	Supplier	Siloxanes and Silicones, di-Me, hydroxy- terminated, reaction products with Me hydrogen siloxanes and trimethoxy(3- (oxiranylmethoxy)propyl)silane	153890-18-7		0.44	mg
			Supplier	1,1'-(Methylenedi-p- phenylene)bismaleimide	13676-54-5		0.99	mg
			Supplier	2,2-Bis(4-hydroxyphenyl)propane- epichlorohydrin copolymer acrylate	55818-57-0		0.22	mg
			Supplier	2,2-dimethyl-1,3-propanediyl dimethacrylate	1985-51-9		0.22	mg
			Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.22	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		0.11	mg
Imaging Lens	29.31	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.5426	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.5426	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		0.1545	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.5426	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.5426	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.5426	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		21.4426	mg
Lid Attach	1.52	mg	Supplier	2,2-Bis(glycidyloxyphenyl)propane polymer	25085-99-8		0.38	mg
			Supplier	3,4-EPOXYCYCLOHEXYLMETHYL	2386-87-0		1.102	mg
			Supplier	Misc.	Proprietary Data		0.038	mg
Mold Compound	8.1	mg		Epoxy resin	proprietary data		2.0088	mg
			Supplier	Other Additive Agents	Proprietary Data		0.2592	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.81	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.779	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.243	mg
Solder Ball	24.55	mg	Supplier	Silver (Ag)	7440-22-4		0.7365	mg
			Supplier	Tin (Sn)	7440-31-5		23.6907	mg
			Supplier	Copper (Cu)	7440-50-8		0.1227	mg

Solder Mask	2.06	mg		Epoxy resin	proprietary data	0.2472	mg
			Supplier	Acrylate	Proprietary Data	0.7869	mg
			Supplier	Talc	14807-96-6	0.0556	mg
			Supplier	Miscellaneous	Trade Secret	0.0762	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	0.894	mg
Substrate Copper Foil	1.59	mg	Supplier	Copper (Cu)	7440-50-8	1.59	mg
Substrate - Core Material	7.88	mg		Epoxy resin	proprietary data	1.7076	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3	6.1724	mg
Substrate Plating-Au	0.14	mg	Supplier	Gold (Au)	7440-57-5	0.14	mg
Substrate Plating-Cu	7.1	mg	Supplier	Copper (Cu)	7440-50-8	7.1	mg
Substrate Plating-Ni	0.33	mg	В	Nickel (Ni)	7440-02-0	0.33	mg
Wire Bond - Au	0.25	mg	Supplier	Gold (Au)	7440-57-5	0.25	mg